

# Mechanics & Cooling Expressions of Interest

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04/09/2019

CERN

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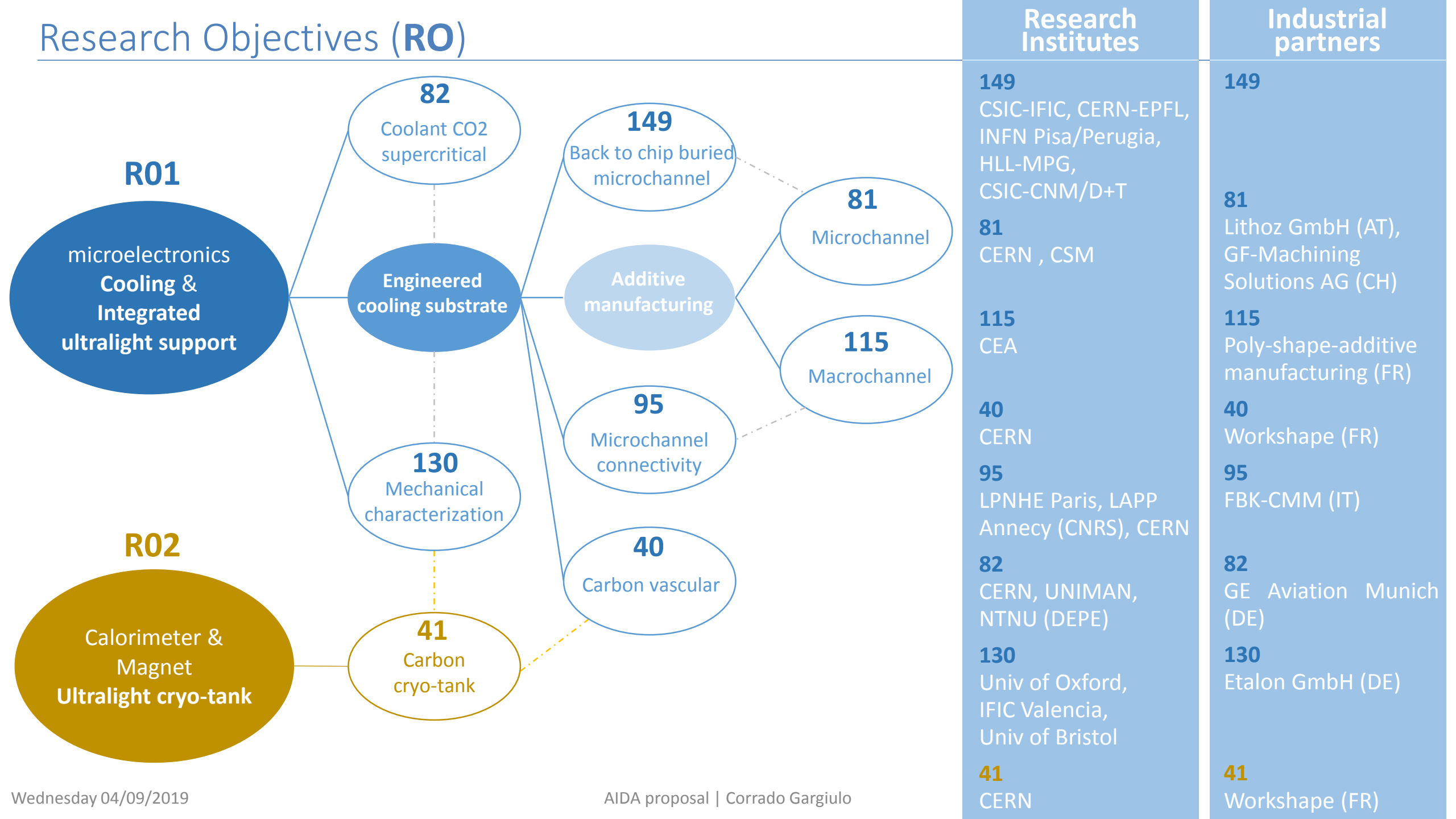
# Expressions of Interest

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## Mechanics & Cooling

- **40.** Development of ultra-light composite structures with fully integrated cooling
- **41.** Development of ultra-light tanks and pipes for cryogenic fluid and high vacuum applications
- **81.** Ultra-light 3D-printed cold plates for vertexing and tracking detectors
- **82.** Super-Critical CO<sub>2</sub> as high performance single-phase refrigerant
- **115.** Design and tests of a cooling plate for 2-phase CO<sub>2</sub> cooling in additive manufacturing
- **130.** R&D and performance verification for mechanical support structures for future vertex-tracking detectors
- **149.** Sculpting in silicon: advanced support and micro-channel cooling solutions

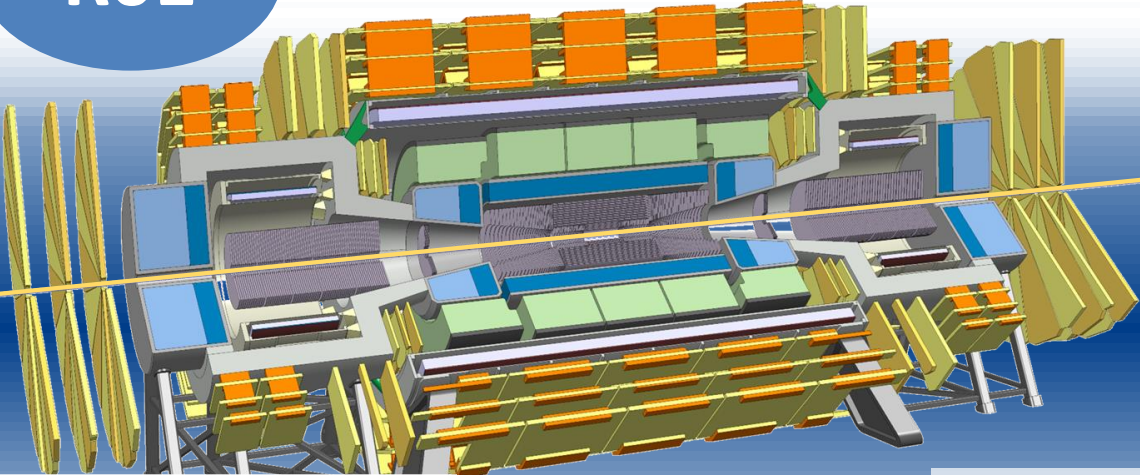
# Research Objectives (RO)



Research Institutes	Industrial partners
<b>149</b> CSIC-IFIC, CERN-EPFL, INFN Pisa/Perugia, HLL-MPG, CSIC-CNM/D+T	<b>149</b>
<b>81</b> CERN , CSM	<b>81</b> Lithoz GmbH (AT), GF-Machining Solutions AG (CH)
<b>115</b> CEA	<b>115</b> Poly-shape-additive manufacturing (FR)
<b>40</b> CERN	<b>40</b> Workshape (FR)
<b>95</b> LPNHE Paris, LAPP Annecy (CNRS), CERN	<b>95</b> FBK-CMM (IT)
<b>82</b> CERN, UNIMAN, NTNU (DEPE)	<b>82</b> GE Aviation Munich (DE)
<b>130</b> Univ of Oxford, IFIC Valencia, Univ of Bristol	<b>130</b> Etalon GmbH (DE)
<b>41</b> CERN	<b>41</b> Workshape (FR)

R01

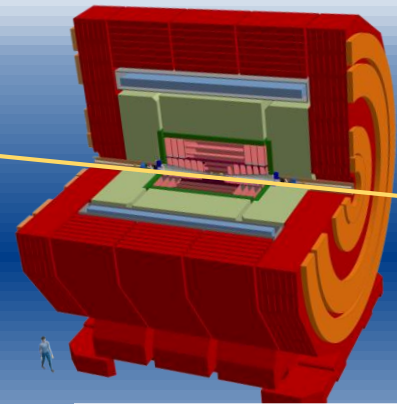
# High-performance cooling & integrated ultralight support for future detectors



FCCh, HE-LHC, ...

hh collisions

e<sup>+</sup>e<sup>-</sup> collisions



CLIC, FCCee, ILC, CEPC,...

- High radiation dose (~ 100 MGy/10years)



- Unprecedented spatial resolution (1-5 μm point resolution)
- Low dissipated power (<50mW/cm<sup>2</sup>)

**Very Low Temperature**  
**High Pressure**

**Room Temperature**  
**Minimum Material budget**

**gas** Air, Nitrogen, He suitable for low on-detector dissipation

**mono phase** WATER "leakless", FKs, NOVEC, sCO<sub>2</sub>

**two phase** CO<sub>2</sub> CO<sub>2</sub>/N<sub>2</sub>O, HFOs

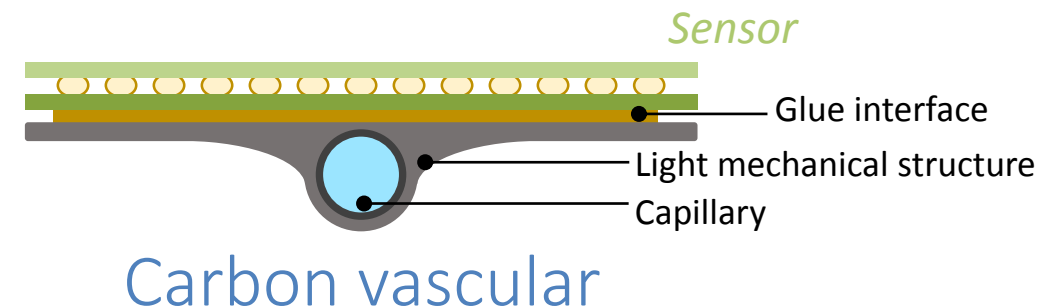
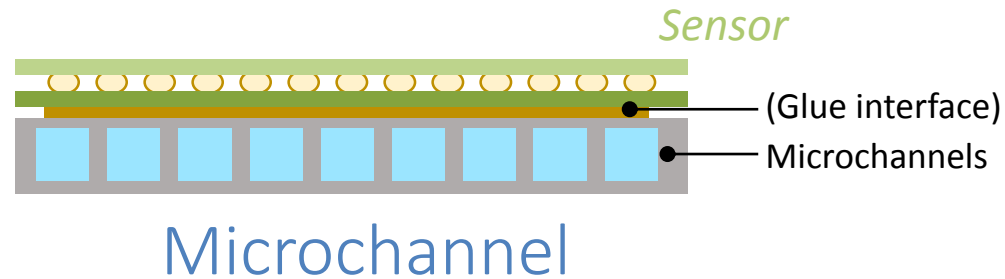
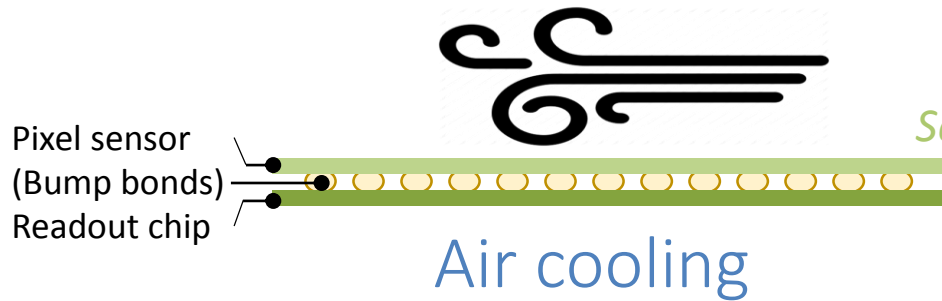
- ✓ Future lepton collider ambient temperature viable solution: air cooling or liquid cooling for complex detector geometry
- ✓ Future hadron collider, more powerful cooling and also lower coolant temperature: CO<sub>2</sub>/N<sub>2</sub>O, HFOs, NOVEC?

# Engineered cooling substrate

to cool and keep in position next generation sensors

R01

- ✓ The design of new vertex detectors in lepton collider will have to cope with unprecedented requirements on minimum material budget and dimensional stability. Reduction of material in front of the sensor will be pursued by investigating new air cooling solutions

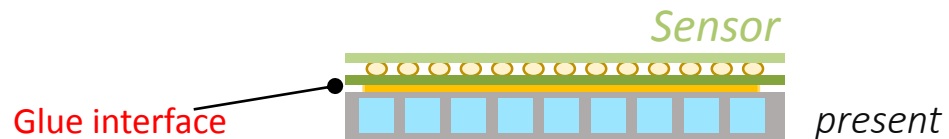
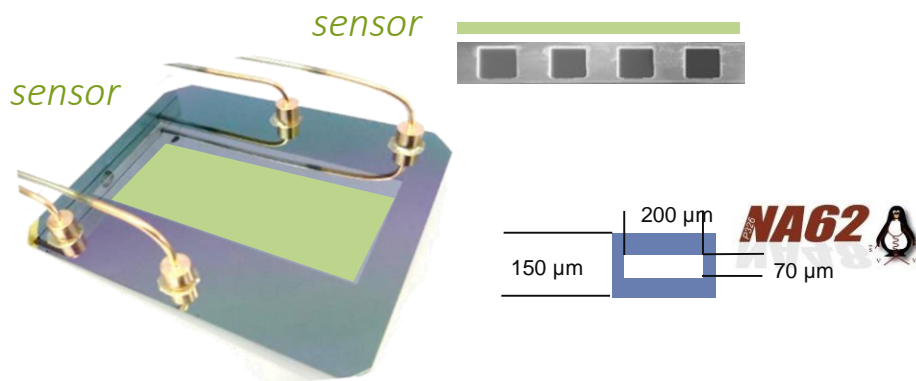


- ✓ In hadron collider vertex detectors stringent cooling requirements, driven by the minimisation of radiation damages, will require the development of new heat exchanger substrates to achieve better performance and lower temperatures

# Back to chip buried microchannels

CSIC-IFIC, CERN-EPFL, INFN Pisa/Perugia, HLL-MPG, CSIC-CNM/D+T

Cold plate: silicon microchannel

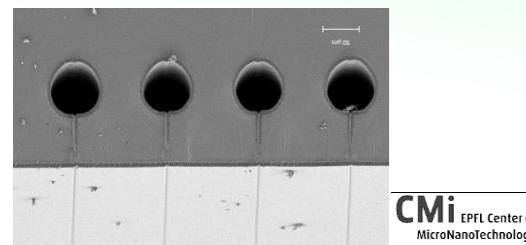
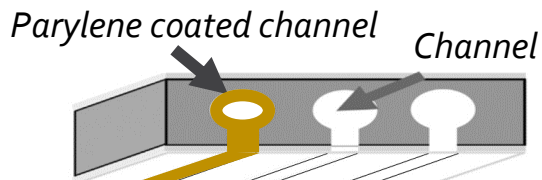
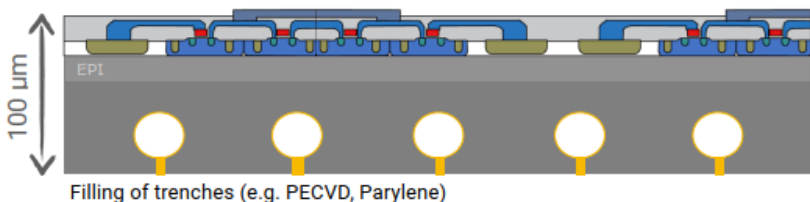


✓ Silicon microchannel substrate glued at the back of the sensor are integrated in HEP Detectors

R&D

Engrave cooling micro channels and supporting structure directly on the back of the chip

- Demonstrator for the key process steps and process identification
- Demonstrator for integrated CMOS ladders with embedded microchannel

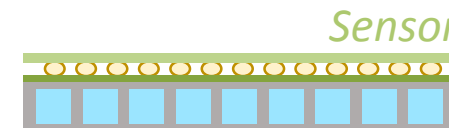


Tests on MALTA chip

future

**Techniques:**

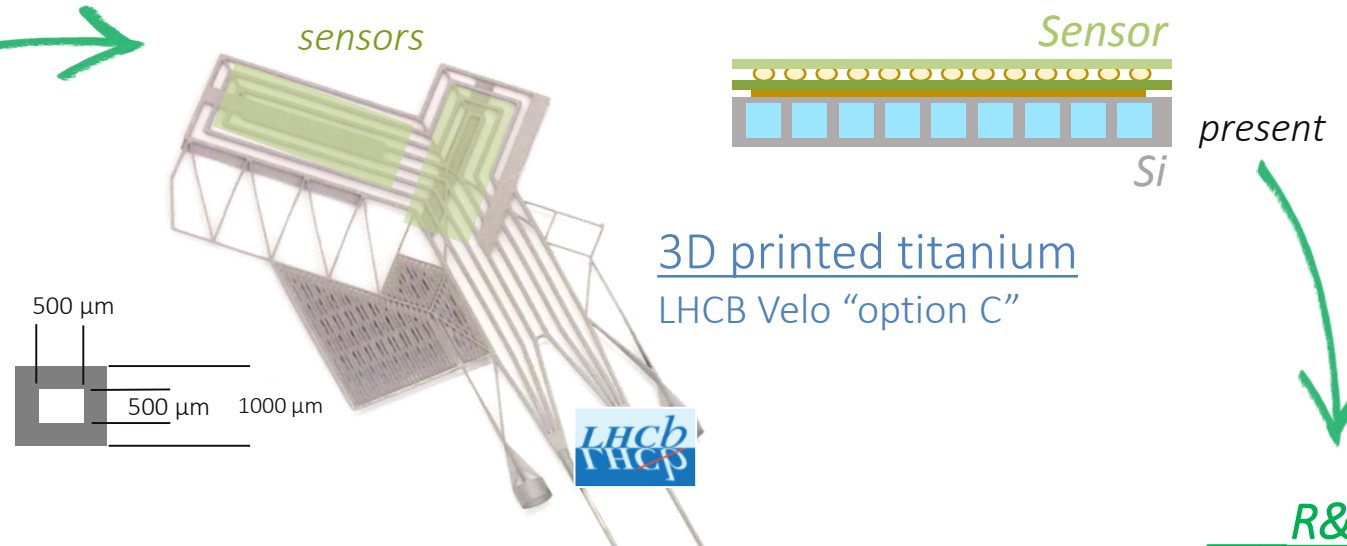
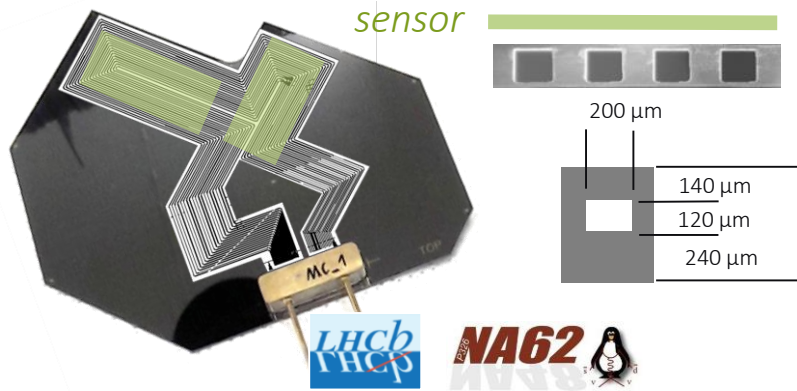
- Selective etching and thinning of CMOS detectors
- Microchannel in silicon plates with integrated signal and power
- Wafer level post processing to incorporate microchannels in CMOS sensors



# Additive manufacturing: micro-channels

CERN , CSM; Lithoz GmbH (AT), GF-Machining Solutions AG (CH)

Cold plate: silicon microchannel



3D printed titanium  
LHCb Velo "option C"

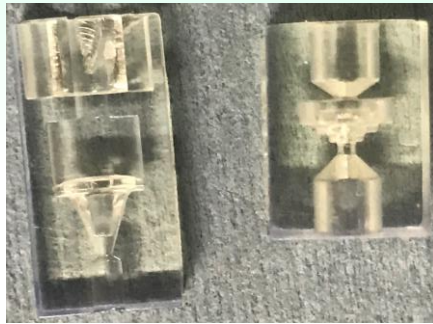
R&D

*develop cheap and non-planar microchannel substrate*

- Investigate additive manufacturing processes
- material engineered for compatibility with Silicon sensors (metal, polymer, ceramics)
- Build working prototypes 3d printed in metal ceramics and polymer
- use of AIDA test facilities

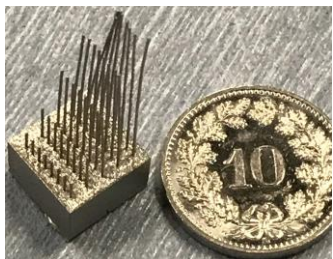


polymer fluidic channels 3D printed on the back of a working CMOS chip



3D printed polymer micro-valves (can be actuated)

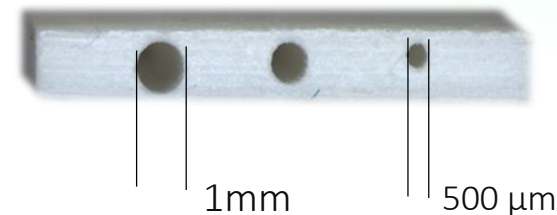
Images COURTESY CSEM



3D printed SS slender pillars



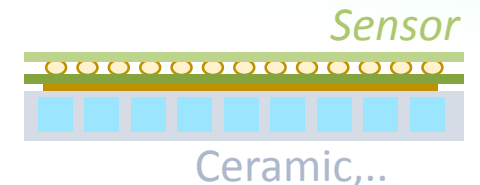
3D printed SS tube with openings (2.5 mm OD, 100 μm thick)



CERN EP-DT  
3D printed ceramic cold plate

1mm 500 μm

future



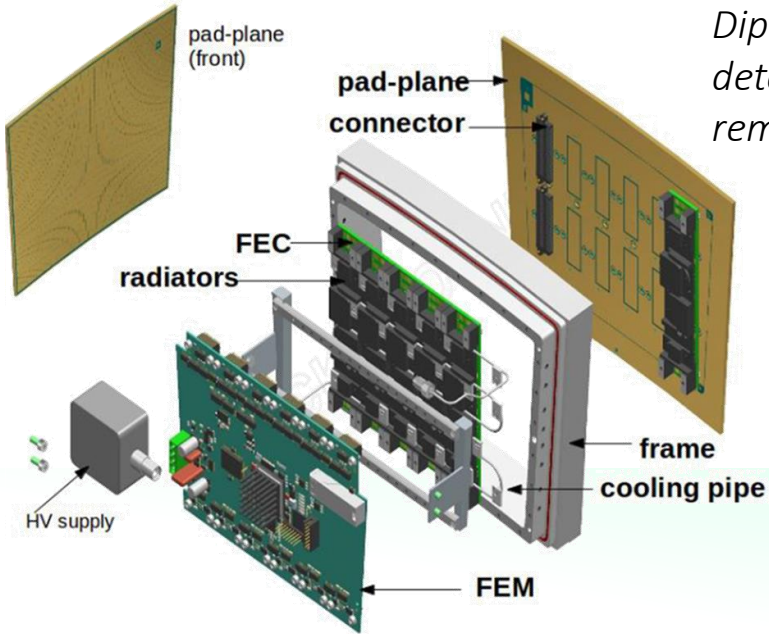
Ceramic,..

# Additive manufacturing: macro-channels

CEA, Poly-shape-additive manufacturing (FR)

✓ Detectors at future accelerators require more efficient cooling for their electronics. Diphasic CO<sub>2</sub> allows a cooling at negative temperature as required by silicon detectors, or at room temperature as needed for TPCs. 2-phase CO<sub>2</sub> cooling allows removing heat at nearly room temperature in a pipe at 50-60 bar

← The present way of making cooling circuits for TPC front-end electronics at the endplate is to use stainless-steel pipes. Additive manufacturing, allows to include a serpentine in the plate in a more straightforward way.



present

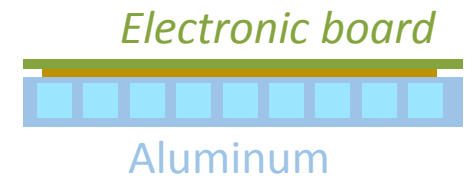
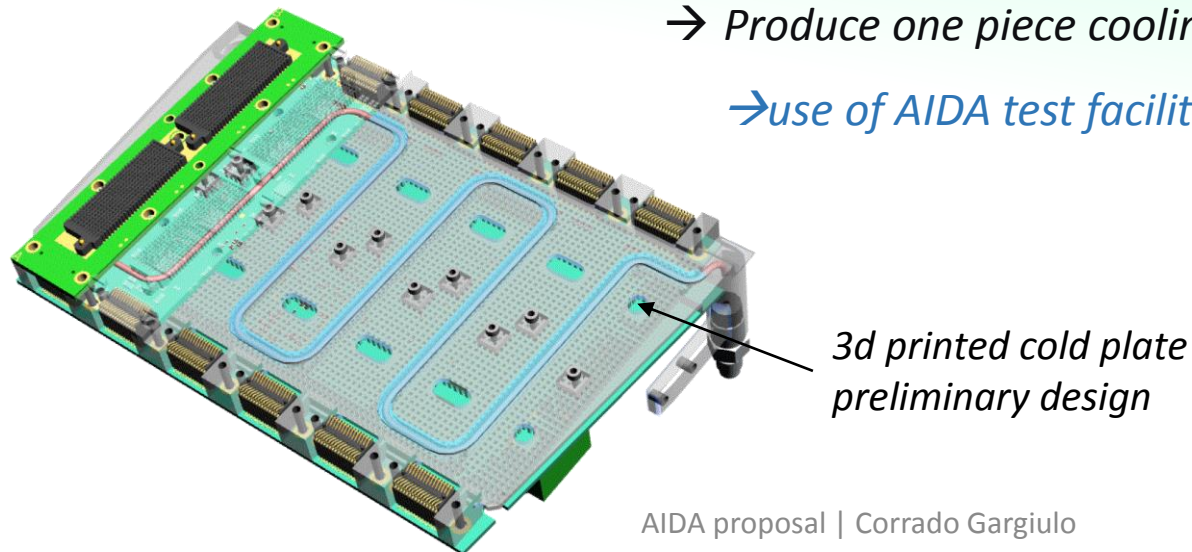


R&D

replace standard cooling pipe circuits with more integrated 3d printed circuits

- Investigate metal (Al) 3d printing processes
- Produce one piece cooling plate 3 d printed in aluminum
- use of AIDA test facility at the DESY test beam facility

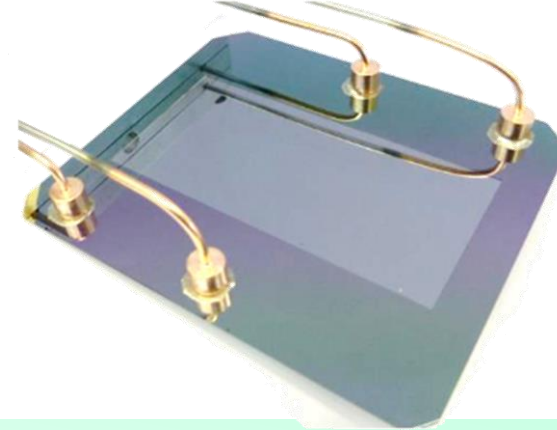
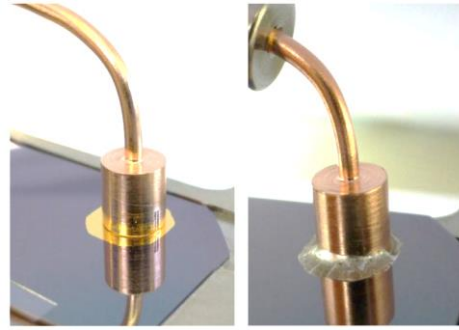
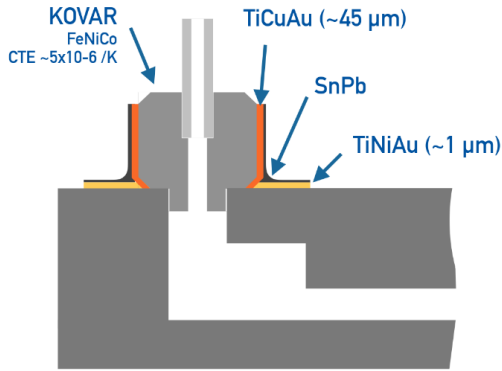
future





LPNHE Paris (CNRS), LAPP Annecy (CNRS), CERN, FBK-CMM

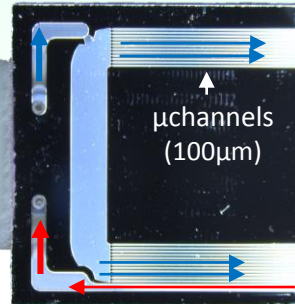
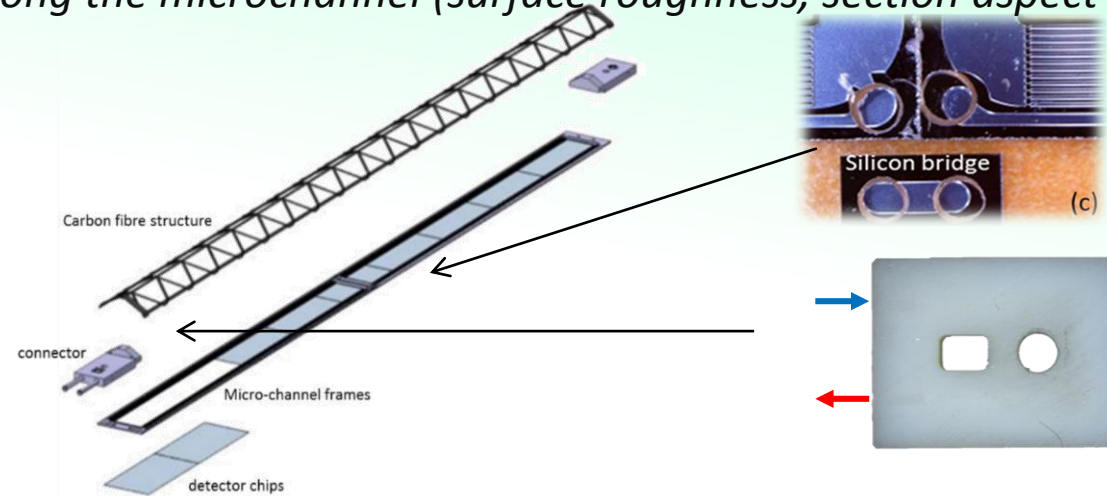
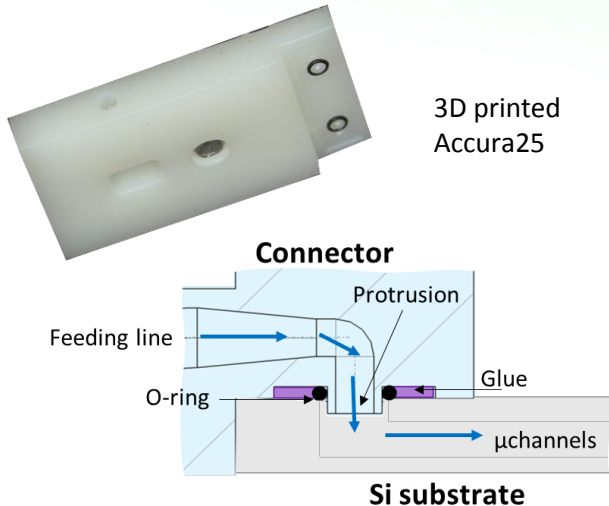
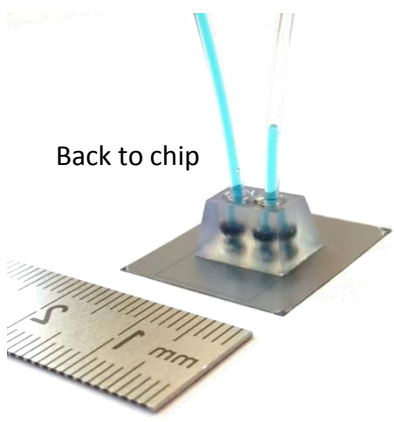
✓ Microchannels are used in experiments such as NA62, with a forward geometry, where connectors can be placed outside the acceptance → robust metal (Kovar) connectors → soldered to pre-metallized silicon → out-of-plane orientation present



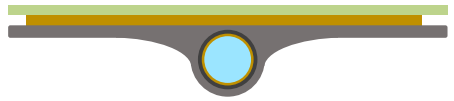
R&D

- Investigate additive manufacturing for lighter microchannel connectivity *Effective microchannel connection with low mass*
- Construction of a large scale cooling system to proof reliability of interconnection
- Methodical study on thermo-dynamical condition along the microchannel (surface roughness, section aspect ratio)

future



Sensor



1mm kapton pipe  
(25um wall)  
available on the medical  
market, used in HEP



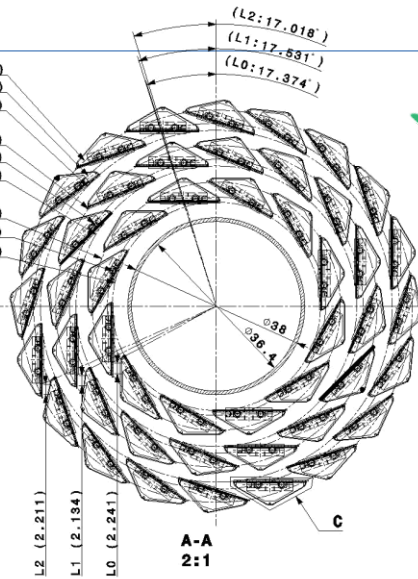
1.7 gram, tested  
up to 50 bar



(L2 Rmax R42.104)  
(L2 Rmid R39.294)  
(L2 Rmin R37.785)

(L1 Rmax R34.545)  
(L1 Rmid R31.538)  
(L1 Rmin R30.139)

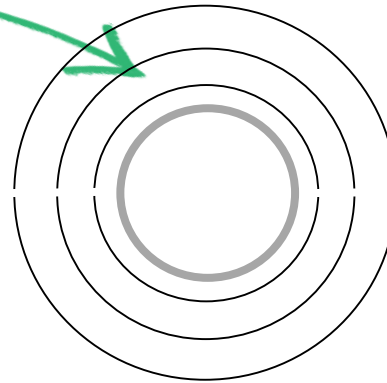
(L0 Rmax R26.661)  
(L0 Rmid R23.443)  
(L0 Rmin R22.379)



A-A  
2:1

R&D

CERN, Workshape(FR)



**Curved Stitched Silicon sensors**

bendable silicon at thickness of about 20–40 μm  
CMOS reticles alignment to produce a larger circuit

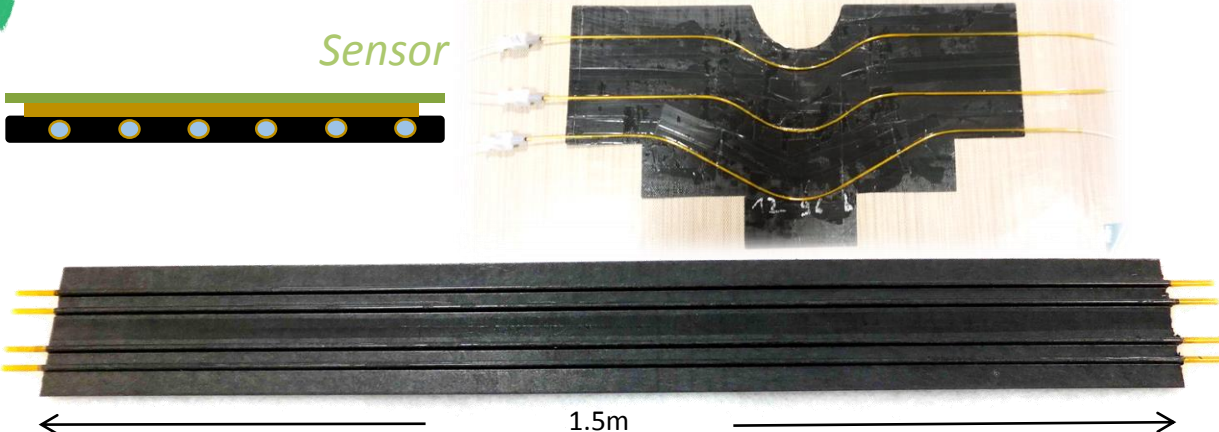
Investigate technologies limits for carbon micro-macro vascular

- Investigate smaller radius/braided pipes: higher pressure (Vertex)
- Investigate longer-multiple pipes: larger surface coverage (Tracker)
- Manufacture and characterize test samples

Develop ultralight carbon support/radiator for air cooling

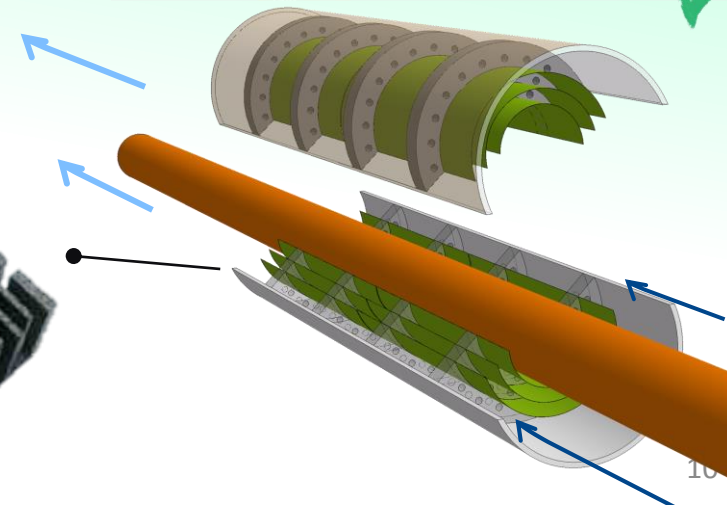
- Sensors hold in place with low-density carbon foam that act as radiator for air cooling
- Manufacture and characterize test samples

Sensor



Sensor

Carbon foam  
heat exchanger



- ✓ For **low radiation environment**, in parallel with gas cooling, **active liquid cooling** systems, operated at **room temperature**, with **minimal impact on material budget**, will be investigated for a more effective solution in complex or packed detector geometries.

Carbon dioxide above the critical point (“sCO<sub>2</sub>”) is in a peculiar phase with gas-like visco-inertial properties, but liquid-like thermo-physical properties: a **super single-phase refrigerant**

*Effective coolant for ambient temperature competitive and alternative to gas cooling*

- knowledge acquisition sCO<sub>2</sub> behavior as ambient temperature coolant
- Improvement of heat exchanger design for sCO<sub>2</sub>
- Full characterization of CO<sub>2</sub>
- Investigation of fluids supercritical state (also for low temperature i.e. Kr)

R&amp;D

future

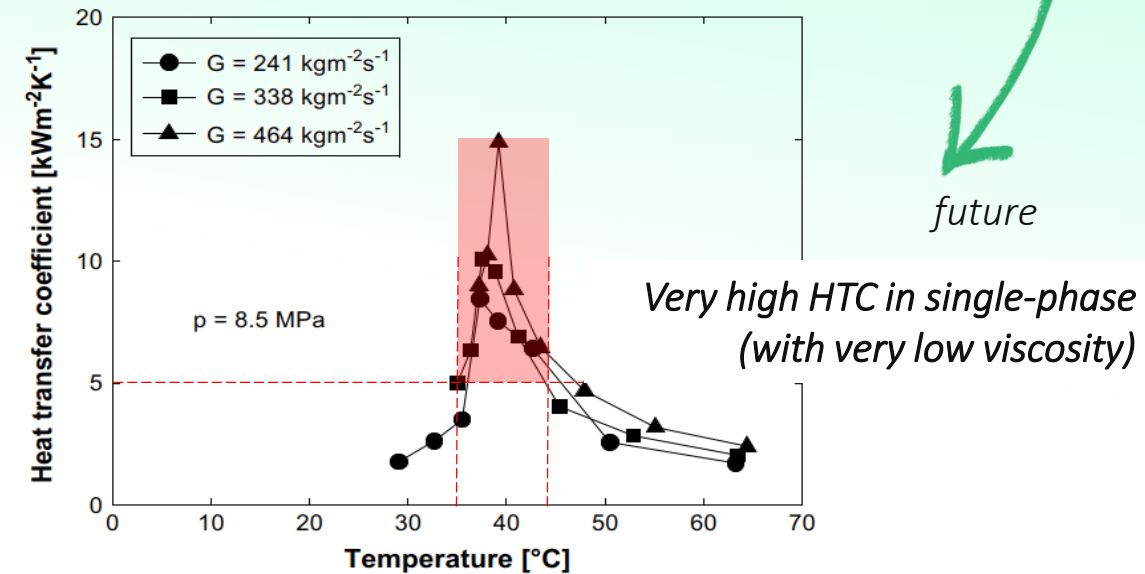
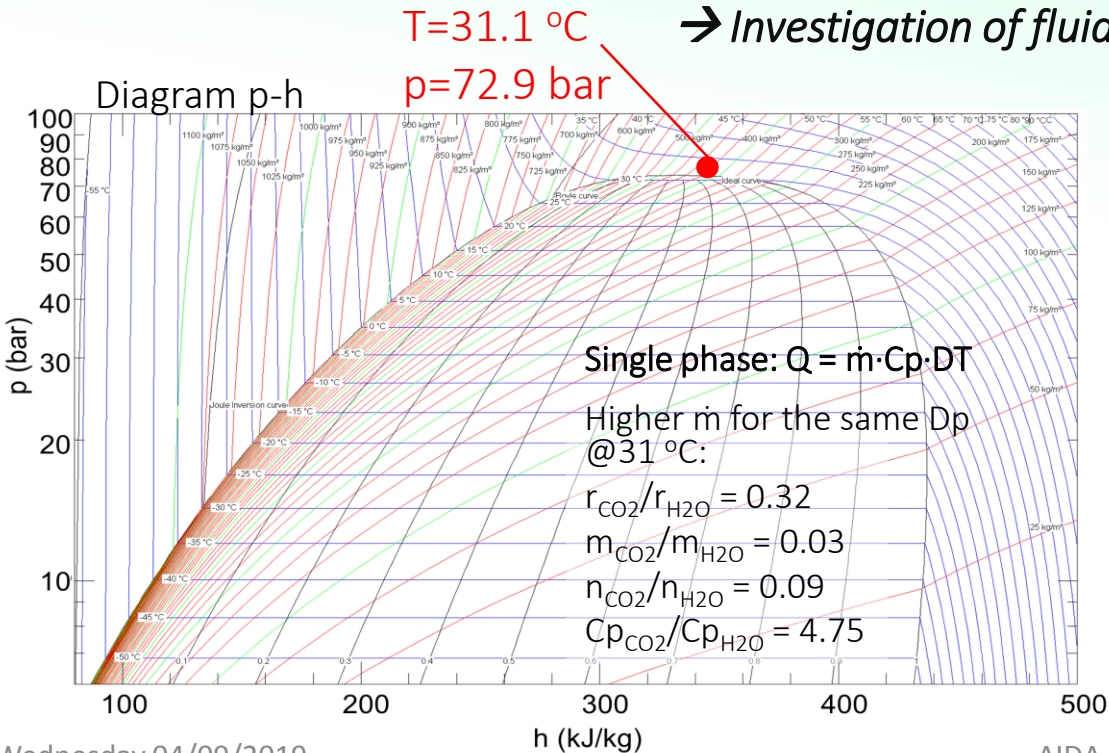
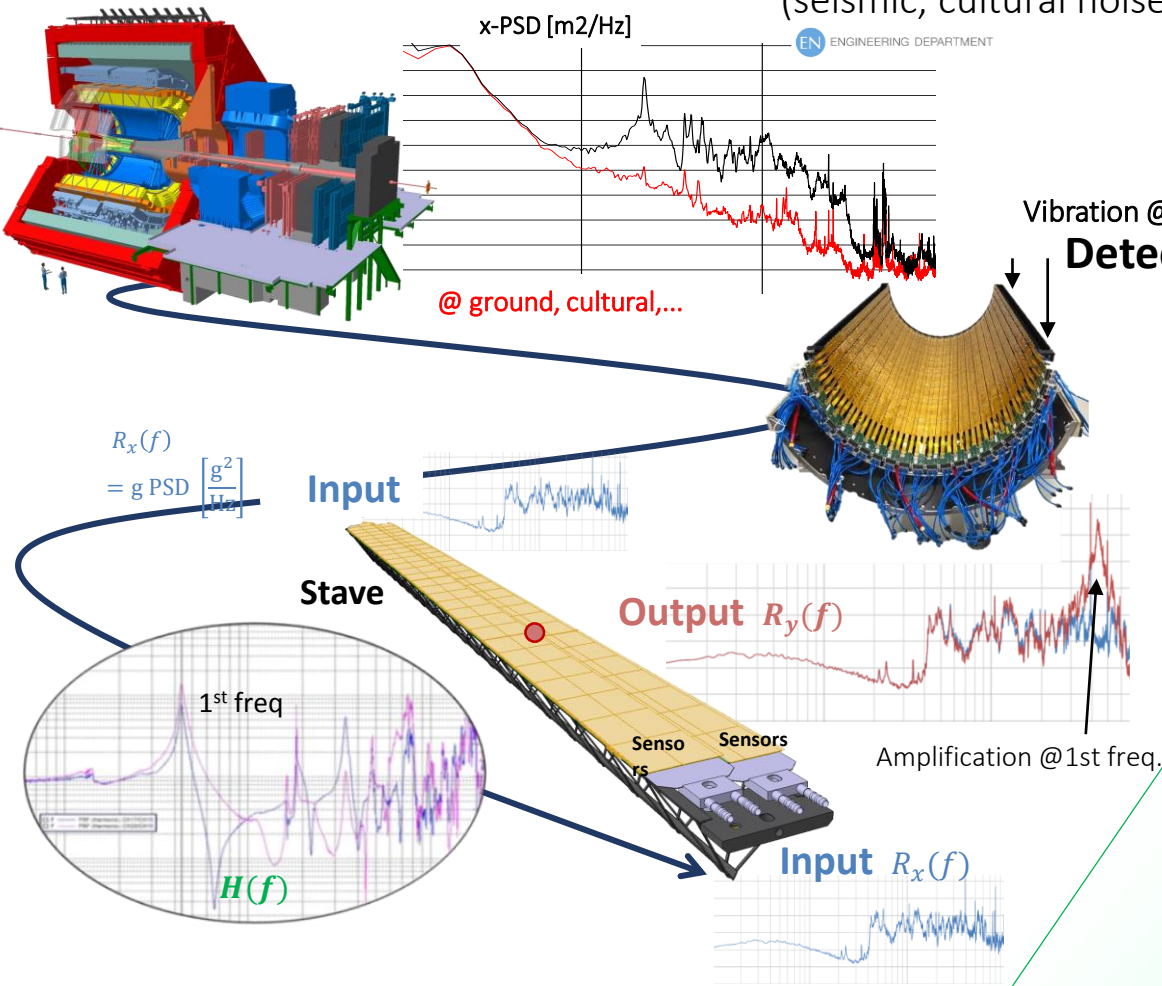
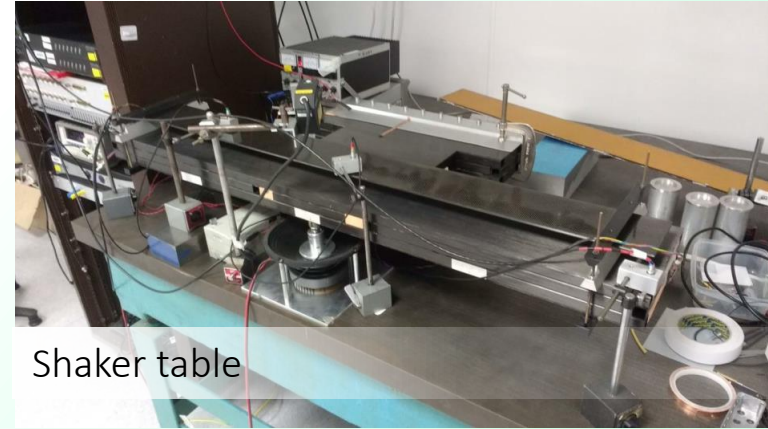


Fig. 3 – Heat transfer coefficient versus bulk temperature for different mass fluxes by Yoon et al. (2003).

- ✓ Predict sensor stability in operative environment, (seismic, cultural noise, air cooling, services,...)



R&D



*Established design criteria and test procedures for ultralight tracker mechanics*

- Improve methodology and survey technologies (touchless probe)
- Full characterization of new developed ultralight structures
- Test procedure and facility available for external users



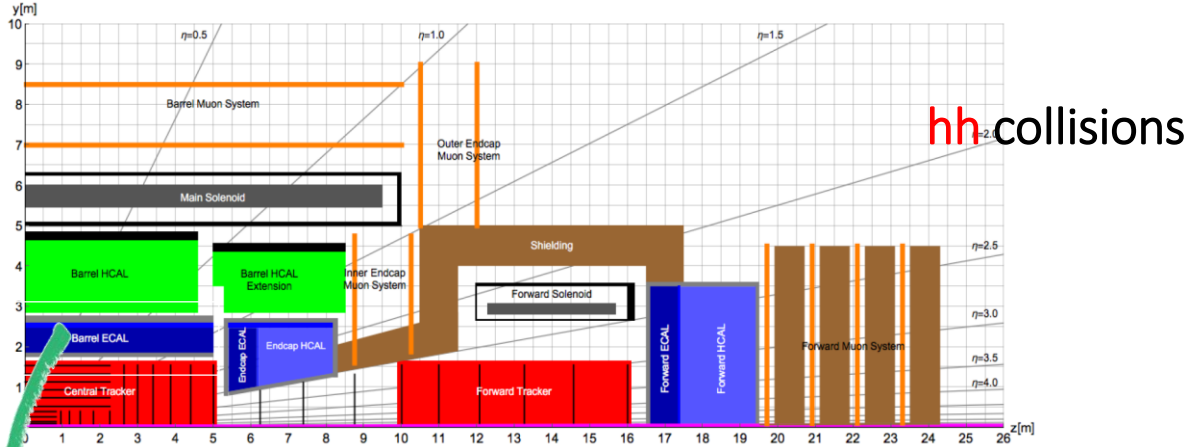
use of AIDA test facility at the University of Oxford

Ultralight mechanical support structures

✓ Cryostats in HEP are still the purview of metals.

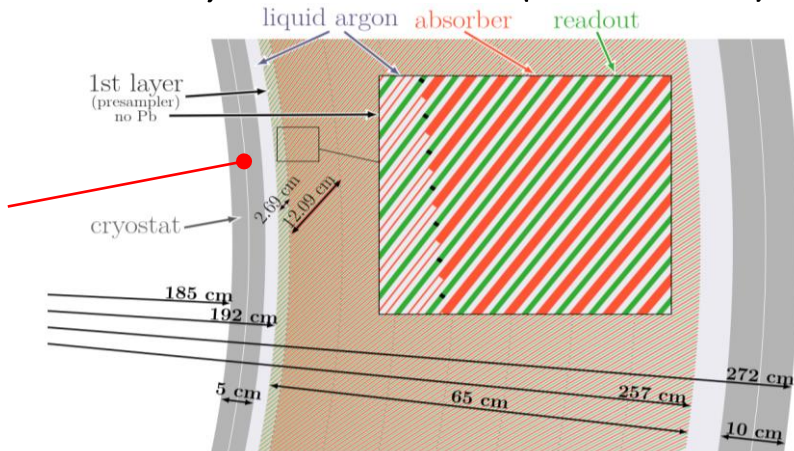
## Baseline geometry, FCC-hh LAr barrel ECAL :

The aluminium cryostat is 5 cm thick, representing 56 % of X0 at  $\eta=0$



### Cryostat calorimeter (double vessel)

minimum material

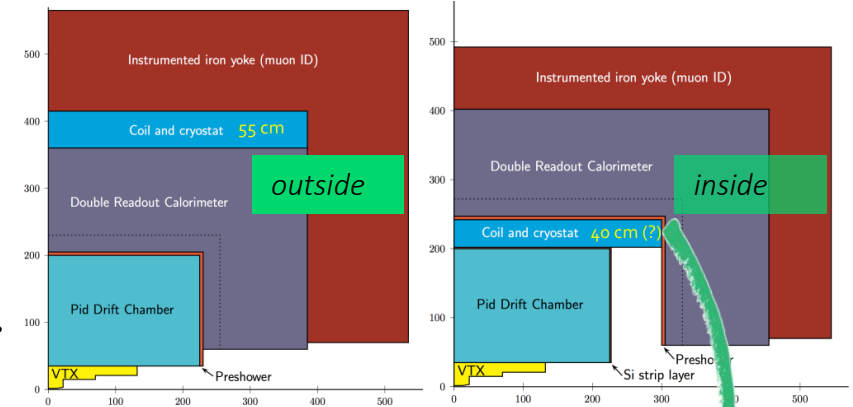


## Baseline geometry, FCC-ee :

a very challenging 2T solenoid “ultra-thin and transparent”

$e^+e^-$  collisions

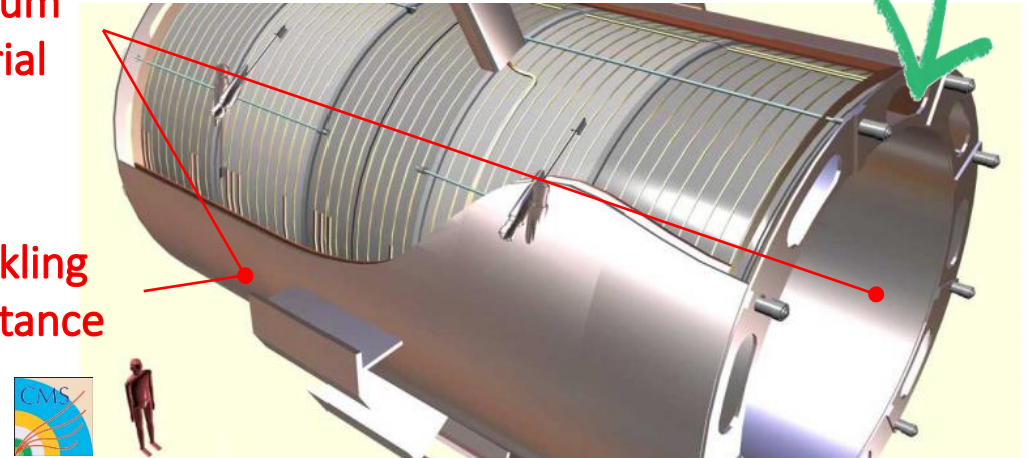
Solenoid  
outside or inside  
calorimeter



### Cryostat magnet

minimum material

buckling resistance



✓ Design solutions based on Carbon Fibre Reinforced Plastic will be investigated to fulfil specific HEP cryostat requirements

# Carbon cryotank: Calorimeters and Detector Magnets

CERN, Workshape(FR)

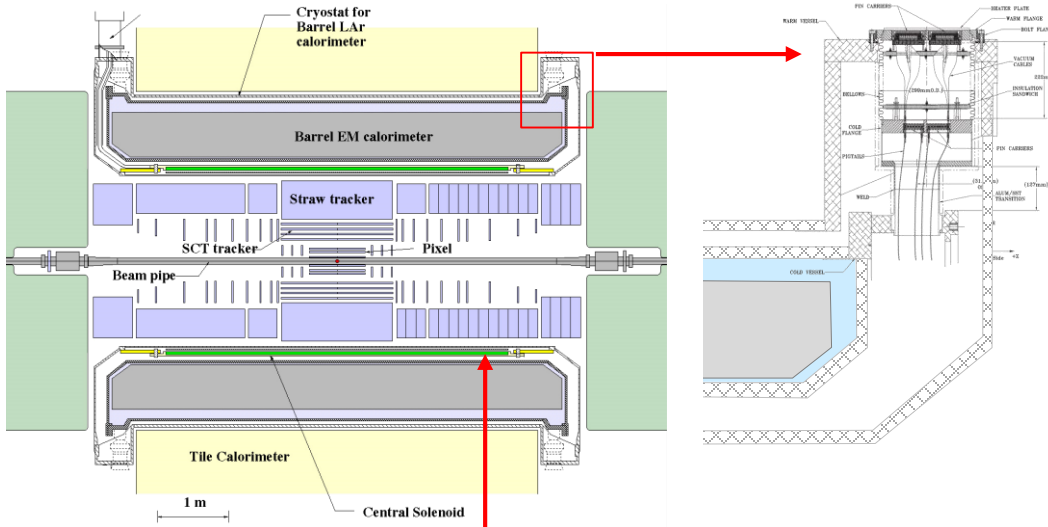
- ✓ New detectors design aims to Ultra Lightweight (ULW) cryostats for both magnets and liquid calorimeter. Use of reinforced Plastic (CFRP) to replace Aluminum will be explored.

*Sensitive material thickness reduction in HEP cryostat in carbon composite*

- ✓ Investigate how to tailor Carbon FRP processes and materials for HEP cryostat: fluid tightness, thermal insulation, feed through, radiation loads
- ✓ Manufacture of samples to validate process and design features



ATLAS Cryostat for the barrel calorimeter.



R&D



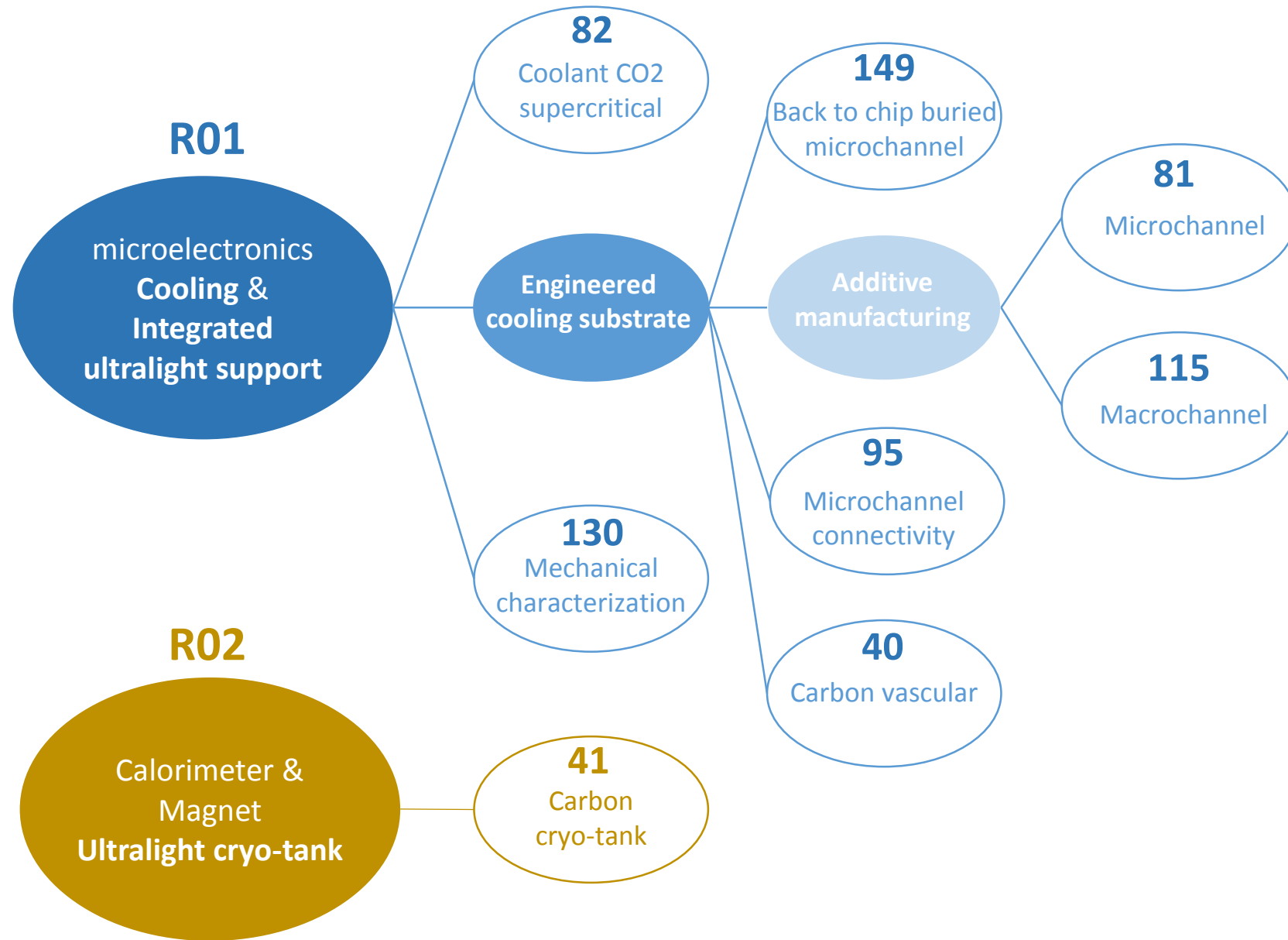
SpaceX ITS LOX tank.

The tank is made of carbon fibres. it is approximately 12 meters in diameter,



# Summary:

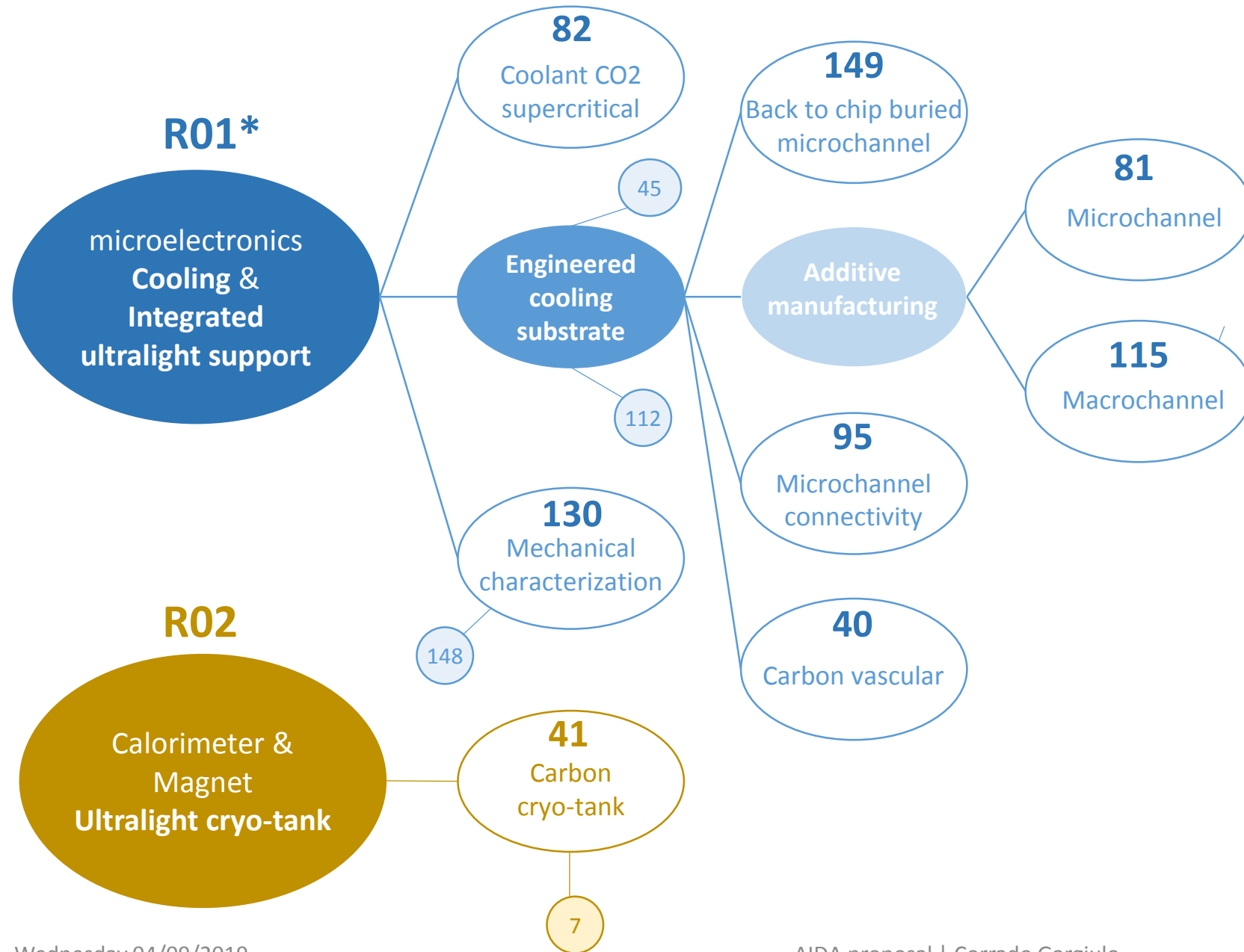
## Added value



- 149**  
Plug & play Chip with integrated cooling and support buried on the back of the sensor
- 81**  
Possibility to develop cheap and non planar microchannel substrate 3d printed
- 115**  
Possibility to replace standard pipe circuit with more integrated 3d printed circuit
- 95**  
Effective connection among microchannels and between microchannels and feeding lines
- 40**  
Unprecedented ultralight thermal/mechanical carbon heat exchanger/support
- 82**  
Effective coolant for ambient temperature competitive and alternative to gas cooling
- 130**  
Established design criteria and test procedures for ultralight tracker mechanics
- 41**  
Sensitive material thickness reduction in HEP cryostat

# Summary:

## Link to other EoIs



The Mechanics and Cooling EoIs are closely connected to several other EoIs, in particular to those looking at the development of novel sensors for future vertex and calorimeter detectors. Few references listed below.

**40, 81, 95, 149**

45 - Ultrathin CMOS pixel modules for precision tracking in high rate e<sup>+</sup>e<sup>-</sup> environment

112-Development of an ultra-thin, wafer-scale CMOS Monolithic Active Pixel Sensor in 65nm technology for applications in tracking and calorimetry

**130**

148-Versatile Assembly, Qualification and Measurement Framework for Complex Detectors

**41**

7-R&D for future high-granularity noble liquid calorimetry

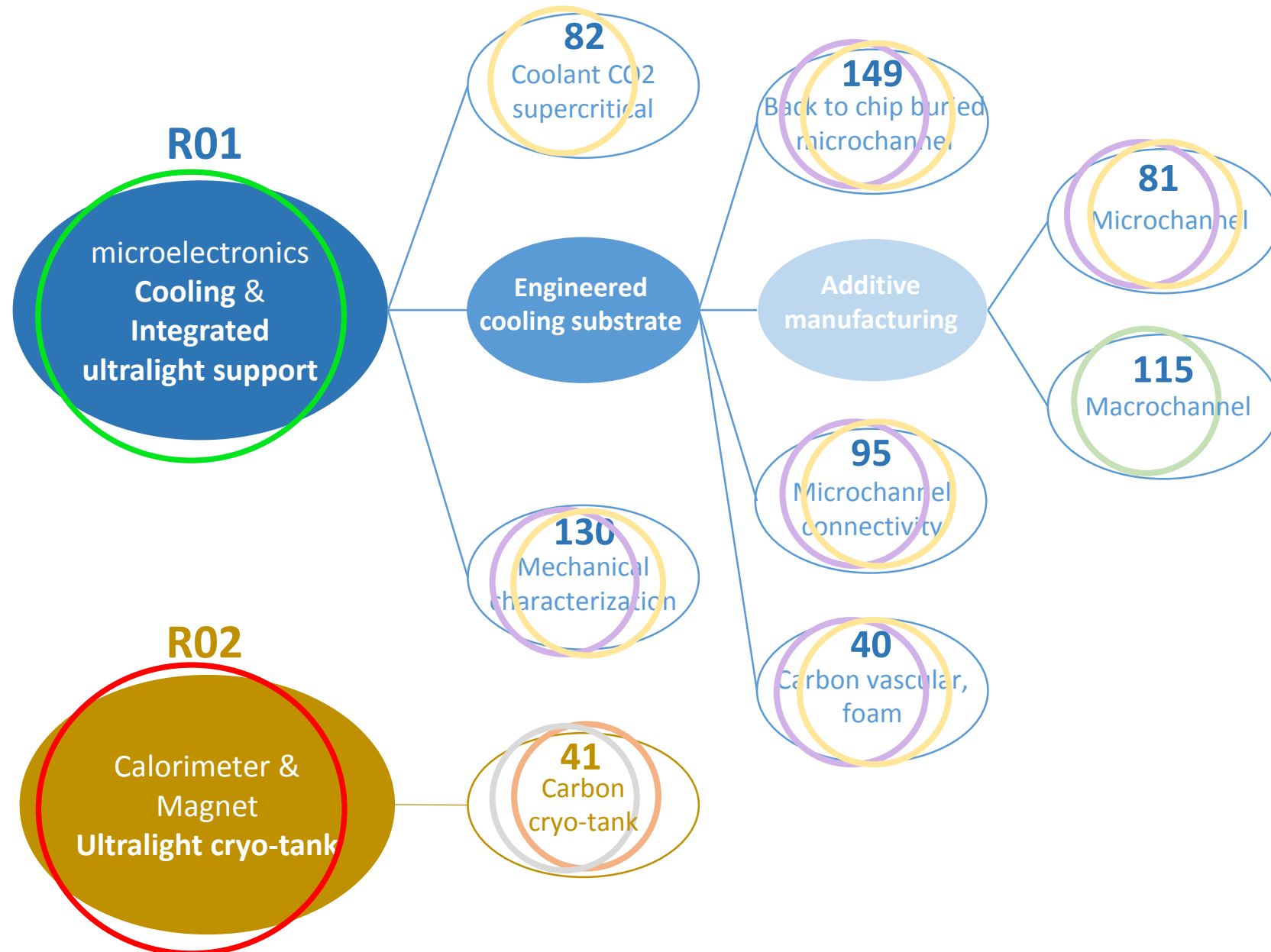
\* Some of the new research activities, will leverage on experimental facilities built in the frame of AIDA2020

Possible synergies with other R&D with CERN EP R&D WP4 (Mechanics) strategic programme on Technologies for Future Experiments

...

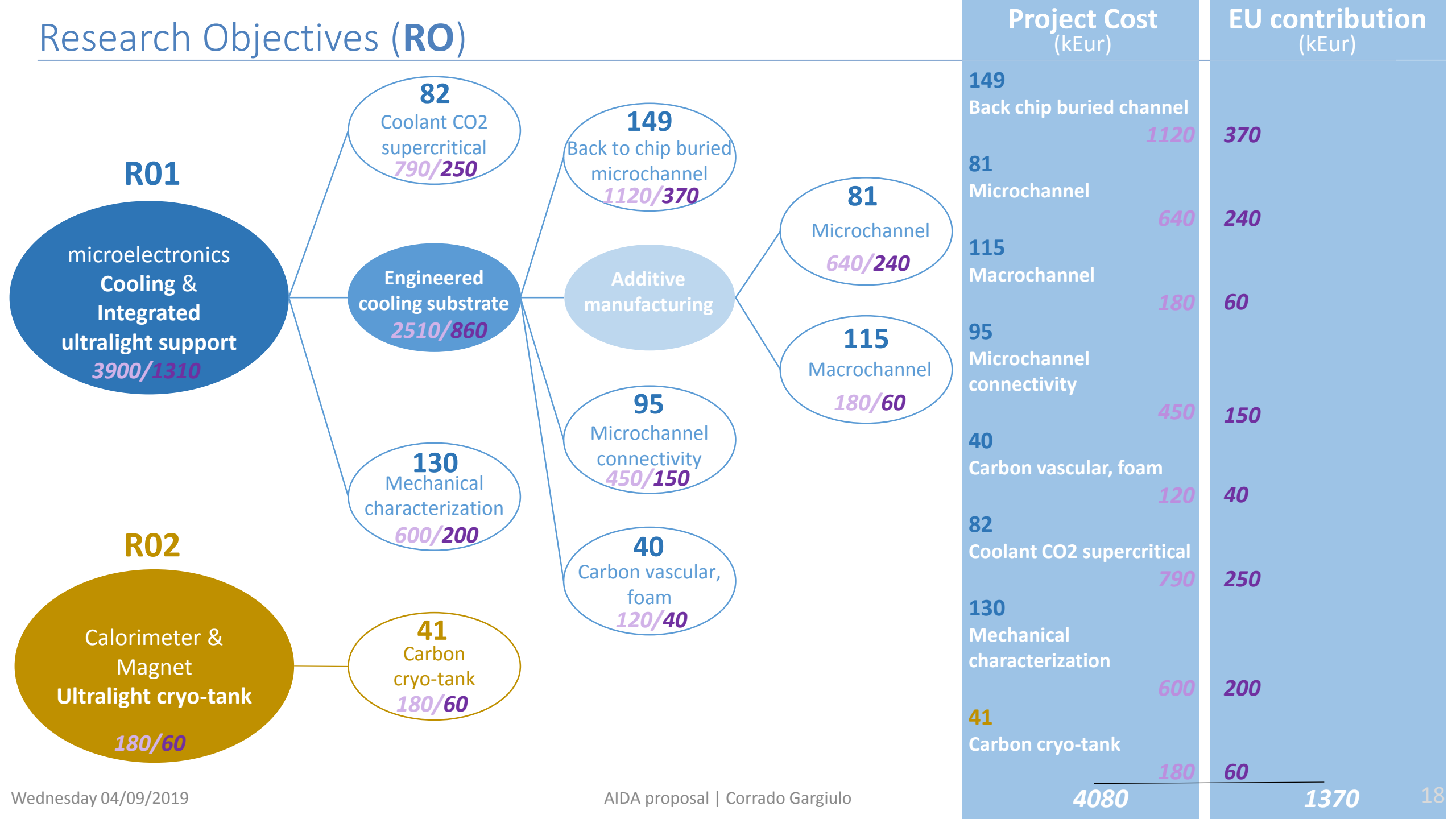


# Summary:



HEP	Other communities
Hadron collider Vertex Tracker	Electronic device
Lepton collider Vertex Tracker	High-Power computing
TPC	bio-medical Lab-on-chip
Liquid Calorimeter	Aerospace satellite
Detector Supercond. Magnet	Aerospace launcher cryo-tank
	Automotive liquefied H2 Transporting (LNG)

# Research Objectives (RO)



	Project Cost (kEur)	EU contribution (kEur)
149 Back chip buried channel	1120	370
81 Microchannel	640	240
115 Macrochannel	180	60
95 Microchannel connectivity	450	150
40 Carbon vascular, foam	120	40
82 Coolant CO2 supercritical	790	250
130 Mechanical characterization	600	200
41 Carbon cryo-tank	180	60
	<b>4080</b>	<b>1370</b>